FIG.1

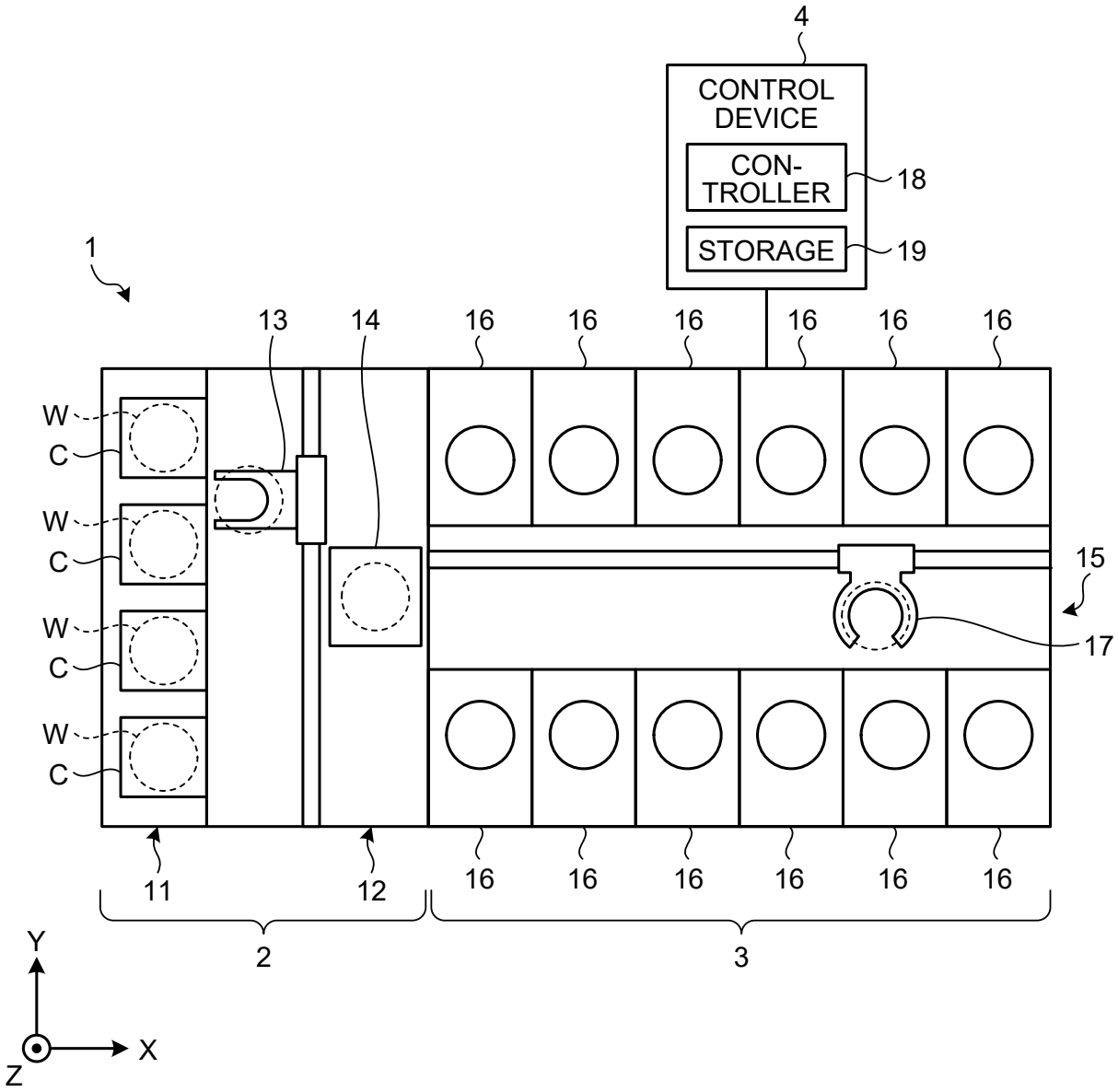

4
CONTROL DEVICE
CON-TROLLER
18
STORAGE
19
1
13
14
16
16
16
16
16
16
W
C
W
C
W
C
W
C
15
17
11
12
16
16
16
16
16
16
2
3
Y
X
Z

FIG.2

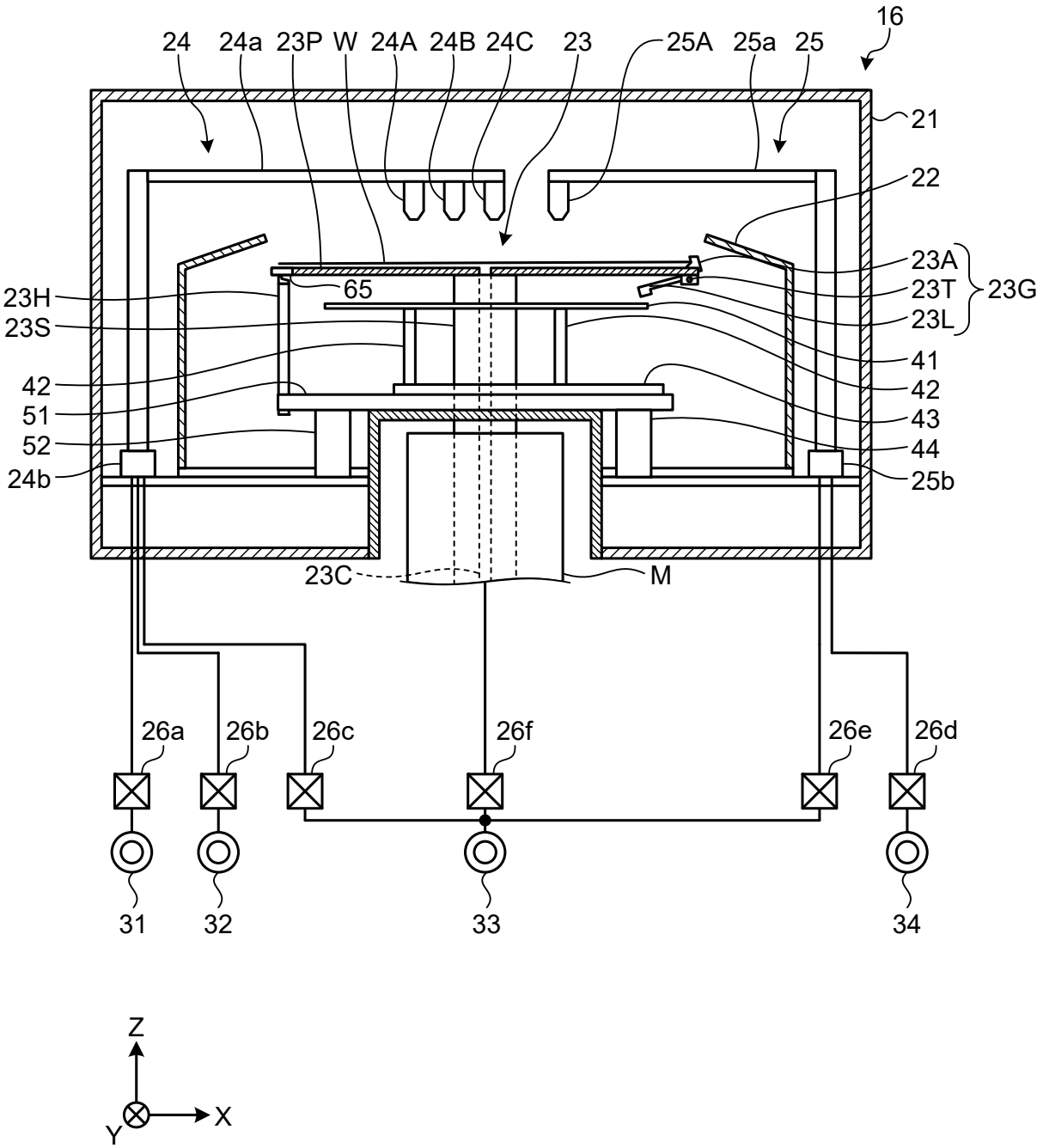

16
24
24a
23P
W
24A
24B
24C
23
25A
25a
25
21
22
23A
23T
23G
23L
23H
23S
65
41
42
51
43
52
44
24b
25b
23C
M
26a
26b
26c
26f
26e
26d
31
32
33
34
Z
X
Y

FIG.3

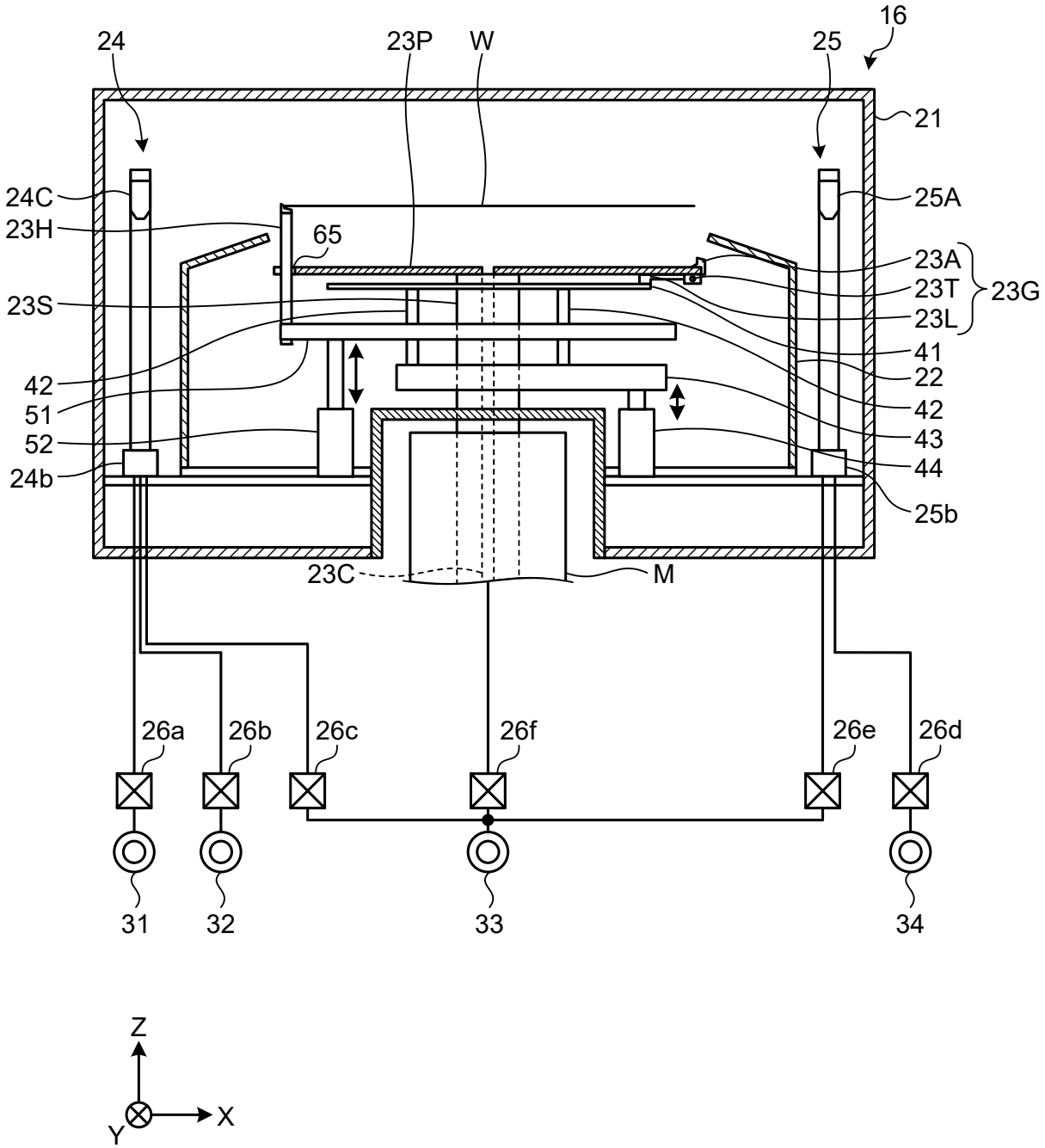

16
24
23P
W
25
21
24C
23H
65
25A
23A
23T
23G
23S
23L
41
22
42
51
52
42
43
24b
44
25b
23C
M
26a
26b
26c
26f
26e
26d
31
32
33
34
Z
X
Y

FIG.4

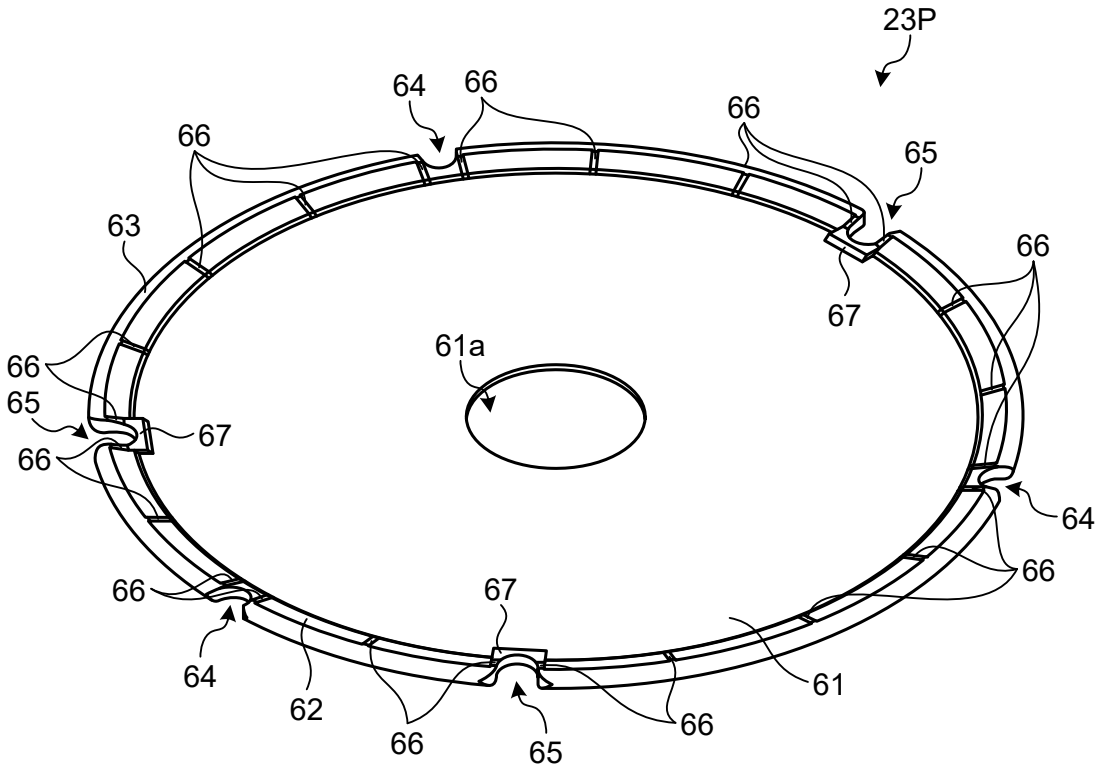

23P
64
66
66
66
65
63
66
67
61a
66
65
67
66
64
66
66
67
64
62
66
65
66
61

FIG.5

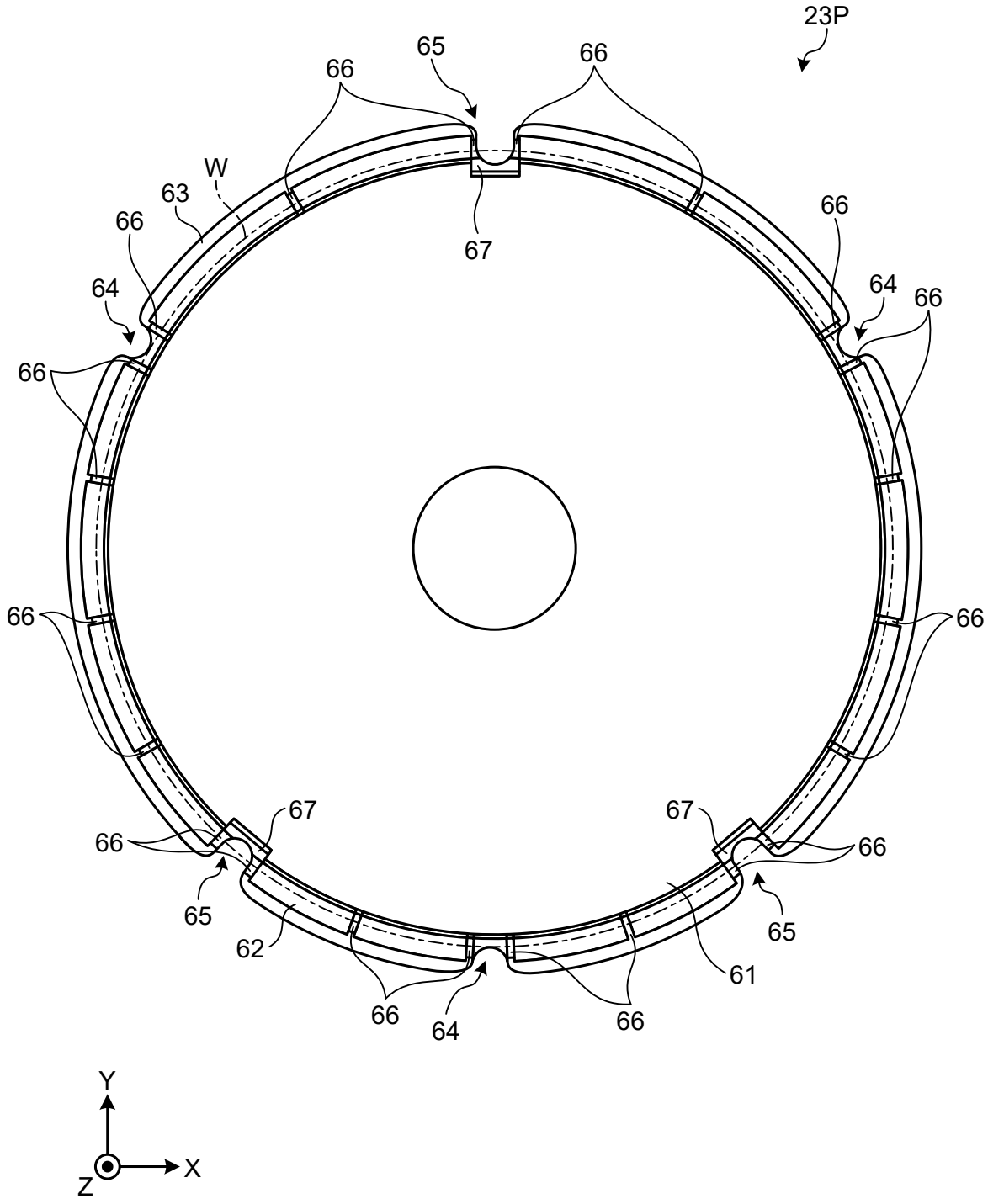

23P
65
66
66
W
63
66
67
66
64
64
66
66
66
66
67
67
66
66
65
65
62
61
66
64
66
Y
X
Z

FIG.6

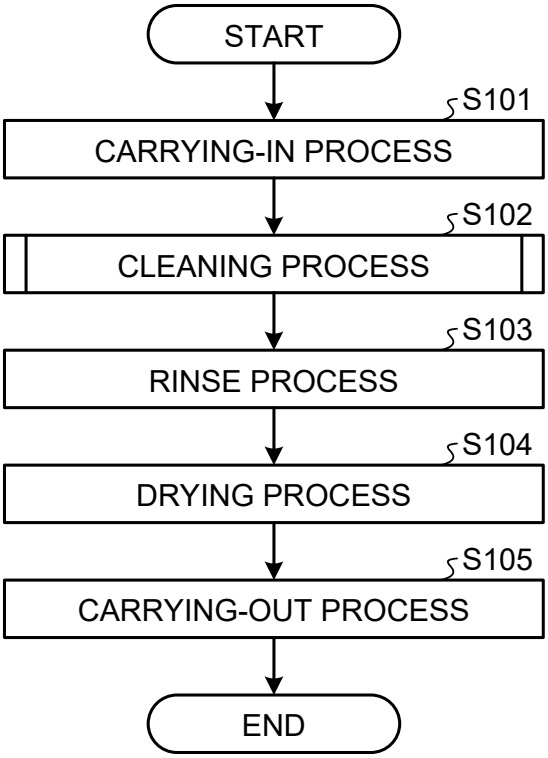

START
S101
CARRYING-IN PROCESS
S102
CLEANING PROCESS
S103
RINSE PROCESS
S104
DRYING PROCESS
S105
CARRYING-OUT PROCESS
END

FIG.7

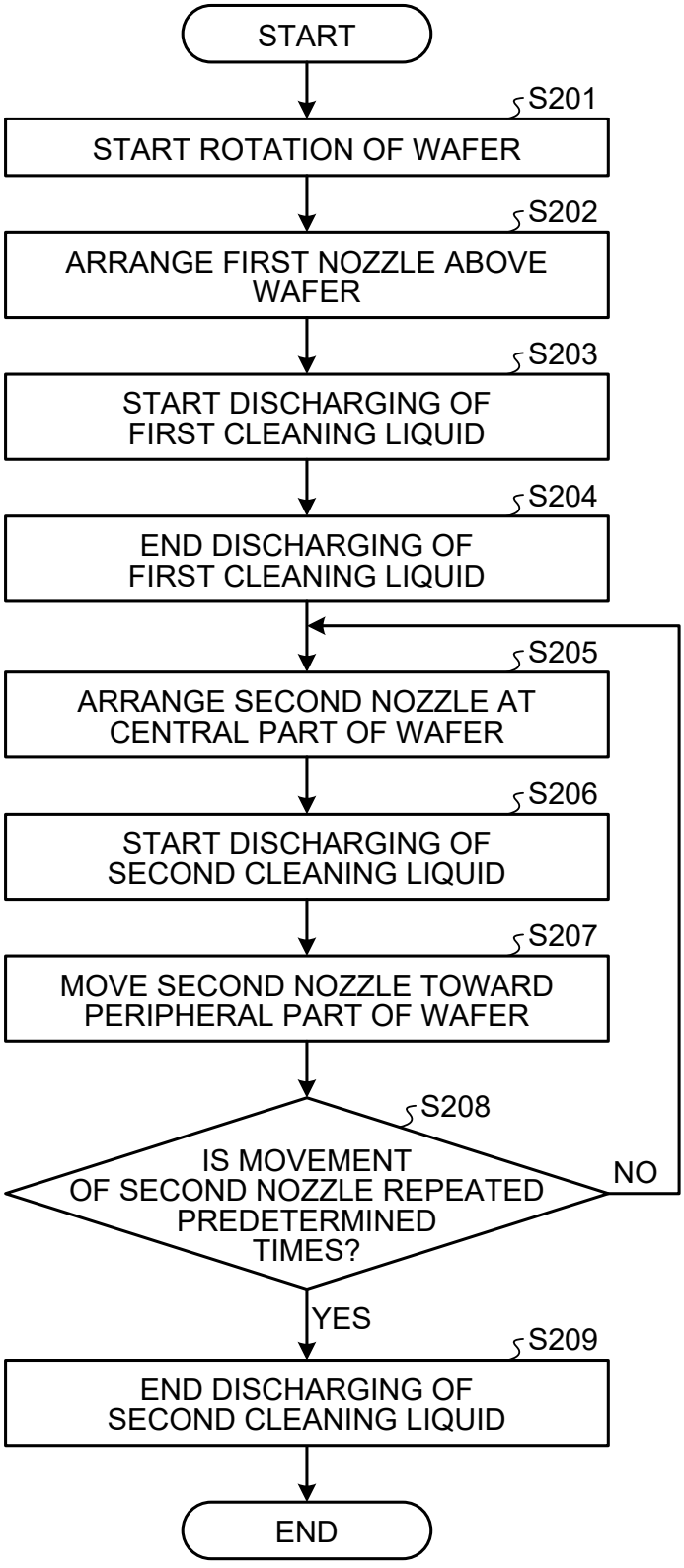

START
S201
START ROTATION OF WAFER
S202
ARRANGE FIRST NOZZLE ABOVE WAFER
S203
START DISCHARGING OF FIRST CLEANING LIQUID
S204
END DISCHARGING OF FIRST CLEANING LIQUID
S205
ARRANGE SECOND NOZZLE AT CENTRAL PART OF WAFER
S206
START DISCHARGING OF SECOND CLEANING LIQUID
S207
MOVE SECOND NOZZLE TOWARD PERIPHERAL PART OF WAFER
S208
IS MOVEMENT OF SECOND NOZZLE REPEATED PREDETERMINED TIMES?
NO
YES
S209
END DISCHARGING OF SECOND CLEANING LIQUID
END

FIG.8

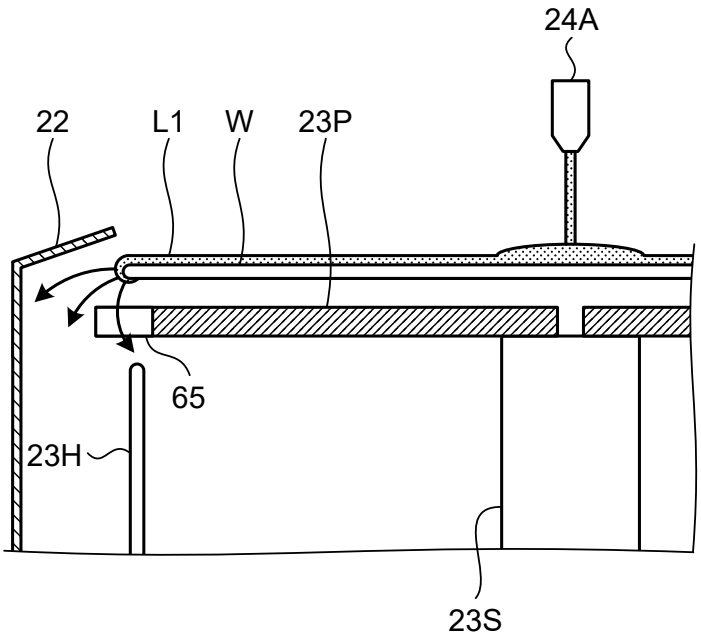


FIG.9

